



IN THE CLAIMS

Please add the following new claim.

*add
a3*
--58. A method for forming an aperture through a layer of fabric of an electronic system support for an electronic circuit board by:

(1) positioning an electronic system support comprising a portion of a layer of fabric comprising a coated fiber strand comprising a resin compatible coating composition on at least a portion of a surface of the fabric, in which an aperture is to be formed in registry with an aperture forming apparatus; and

(2) forming an aperture in the portion of the layer of fabric.--

REMARKS

The amendment to the specification has been made to add two additional pending applications from which the instant application claims priority. The new claim does not include any new subject matter and support can be found at page 78 line 26 through page 79 line 1 of the specification. Applicants respectfully request admission of these amendments.

If there are any questions regarding the above, please contact Applicants' attorney at the telephone number provided below

Respectfully submitted,

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